

## Specifications

Insulation Resistance: 1,000MΩ min. at 500V DC  
 Dielectric Withstanding Voltage: 700V AC for 1 minute  
 Contact Resistance: 30mΩ max. at 10mA/20mV max.  
 Operating Temperature Range: -55°C to +170°C  
 Contact Force: 30g min. per pin at minimum displacement of 0.45mm  
 90g max. per pin at maximum displacement of 0.8mm

## Materials and Finish

Housing: Polyetherimide (PEI), glass-filled  
 Contacts: Beryllium Copper (BeCu)  
 Plating: Gold over Nickel



## Part Number (Details)

NP178 - 644 01 - \* - \*\*

Series No.

No. of Contact Pins

Design Number

Matching IC Diameter /Socket Pin Length

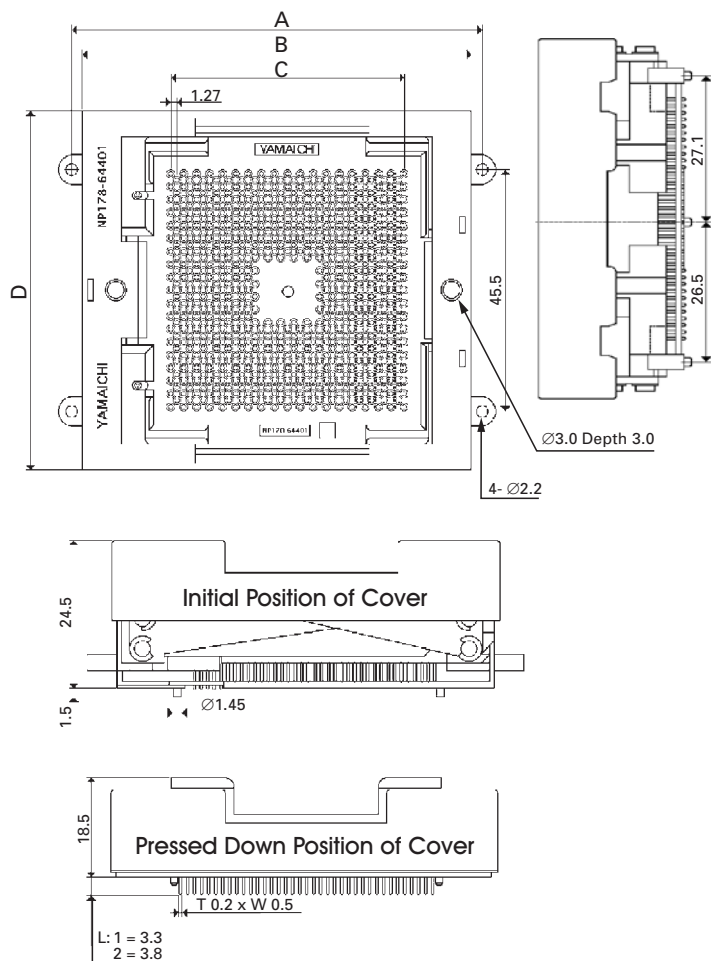
1: ∅0.35±0.05 1: L = 3.3

2: ∅0.45±0.05 2: L = 3.8

MF = Flanged

Unmarked = Not Flanged

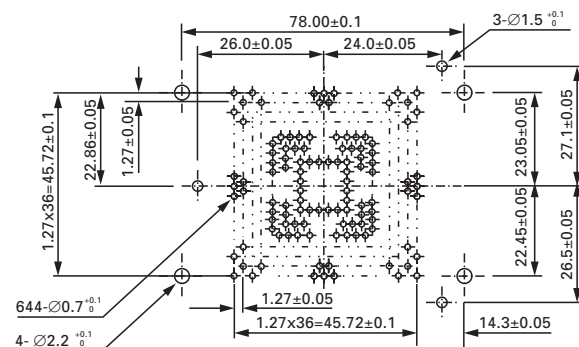
## Outline Socket Dimensions



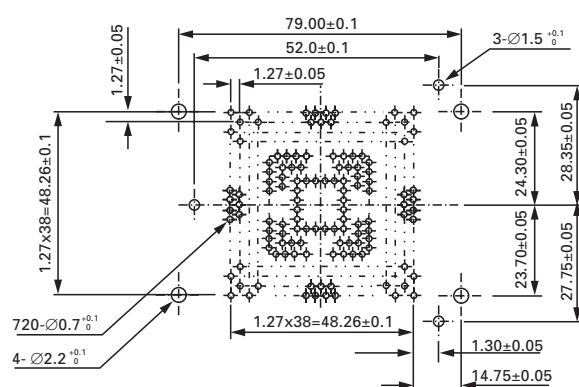
## Recommended PC Board Layout

Top View from Socket

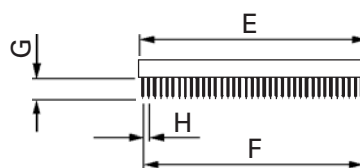
NP178-64401-\*\*-\*\*



NP178-72002-\*\*-\*\*



## Outline IC Dimensions



Part Number	Grid Size	Pin Count	Socket Dimensions				IC Dimensions			
			A	B	C	D	E max.	F	G	H
NP178-64401-**-**	19 x 19	644	78.0	74.0	1.27x36=45.72	67.0	□50.0	45.72	2.54~5.9	1.27
NP178-72002-**-**	20 x 20	720	79.0	75.0	1.27x38=48.26	69.5	□52.8	48.26	2.54~5.9	1.27